













FABRICATION NOTES:

- 1.) MATERIAL SELECTION:
PER LATEST REVISION OF IPC-4101 (OR EQUIVALENT) UL RECOGNIZED ZPMV2 MIN.
130C FLAME CLASS V-0 OR BETTER. .062+/- .007 MATERIAL PER IPC-4101.
3 OZ. COPPER FOR EXTERNAL LAYERS. 2 OZ. COPPER FOR INTERNAL LAYERS.
SOLDERABLE SURFACES TO BE SILVER IMMERSION FINISH.
- 2.) SOLDER RESIST: THE USE OF SOLDER RESIST COATING SHALL BE IN
ACCORDANCE WITH THE REQUIREMENTS OF IPC-SM-840. ALL SOLDERABLE SURFACES
ARE TO BE FREE OF SOLDER RESIST. COLOR - GREEN.
USE LIQUID PHOTOIMAGEABLE RESIST.
- 3.) SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. ALL COMPONENT AND TESTPOINT
LANDS ARE TO BE FREE OF INK.
- 4.) MANUFACTURER'S IDENTIFICATION: ADD IN ETCH OR TO SILKSCREEN.
- 5.) ELECTRICAL BARE BOARD TEST REQUIRED.
- 6.) DRILL SIZES ARE FINISHED SIZE AFTER PLATING.
- 7.) FABRICATE TO MEET EU ROHS DIRECTIVE.
- 8.) PCB MUST HAVE UL 94V-0 AND CTI RATING MARKED ON ONE SIDE.
- 9.) MAX WARP AND TWIST NOT TO EXCEED 0.010 PER LINEAR INCH.
- 10.) MIN ANNULAR RING: 0.003. MIN PLATED HOLE WALL THICKNESS 0.001.
- 11.) DIMENSIONAL TOL: XX +/- 0.010. XXX +/- 0.005.
- 12.) FABRICATE IN ACCORDANCE WITH IPC-600 OR IPC-6012 LATEST REVISION. CLASS 2.
- 13.) COPPER THEIVING OF THE SIGNAL LAYERS IS ALLOWED. SPACING TO ANY EXISTING
BOARD FEATURE TO BE 0.060 MINIMUM.
- 14.) ALL (314) 12.1 DIAMETER HOLES TO BE PLUGGED FROM THE TOP SIDE
(COMPONENT SIDE) WITH EITHER UV OR THERMALLY CURED PLUGGING MATERIAL.
THE PLUGGING MATERIAL SHOULD NOT DRIP OUT THE BOTTOM SIDE OF THE PCB.

DRILL CHART: TOP & BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	12.0	+3.0/-3.0	PLATED	1499
□	12.1	+3.0/-3.0	PLATED	214
○	15.0	+3.0/-3.0	PLATED	3112
⊙	40.0	+3.0/-3.0	PLATED	177
○	55.0	+3.0/-3.0	PLATED	4
◇	72.0	+3.0/-3.0	PLATED	18
△	126.0	+2.0/-2.0	NON-PLATED	8
○	150.0	+2.0/-2.0	NON-PLATED	4
○	152.0	+2.0/-2.0	NON-PLATED	1
□	156.0	+2.0/-2.0	NON-PLATED	5











